Preferred Device

Advance Information

Power MOSFET 10 Amps, 400 Volts N-Channel TO-220 and D²PAK

Designed for high voltage, high speed switching applications in power supplies, converters, power motor controls and bridge circuits.

Features

- Higher Current Rating
- Lower R_{DS(on)}
- Lower Capacitances
- Lower Total Gate Charge
- Tighter VSD Specifications
- Avalanche Energy Specified

Typical Applications

- Switch Mode Power Supplies
- PWM Motor Controls
- Converters
- Bridge Circuits

MAXIMUM RATINGS (T_C = 25°C unless otherwise noted)

Rating	Symbol	Value	Unit		
Drain–Source Voltage	V _{DSS}	400	Vdc		
Drain–Gate Voltage (R_{GS} = 1.0 M Ω)	VDGR	400	Vdc		
Gate–Source Voltage – Continuous – Non–Repetitive (t _p ≤10 ms)	V _{GS} V _{GSM}	±20 ±40	Vdc		
Drain – Continuous – Continuous @ 100°C – Single Pulse (t _p ≤10 μs)	ID ID IDM	10 7.5 35	Adc		
Total Power Dissipation Derate above 25°C	PD	142 1.14	Watts W/∘C		
Operating and Storage Temperature Range	TJ, Tstg	-55 to 150	°C		
Single Drain-to-Source Avalanche Energy – Starting T _J = 25° C (V _{DD} = 100 Vdc, V _{GS} = 10 Vdc, I _L = 10 A, L = 10 mH, R _G = 25Ω)	E _{AS}	500	mJ		
Thermal Resistance – Junction–to–Case – Junction–to–Ambient – Junction–to–Ambient (Note 1.)	R _{θJC} R _{θJA} R _{θJA}	0.88 62.5 50	°C/W		
Maximum Lead Temperature for Soldering Purposes, 1/8" from case for 10 seconds	ΤL	260	°C		

1. When surface mounted to an FR4 board using the minimum recommended pad size.

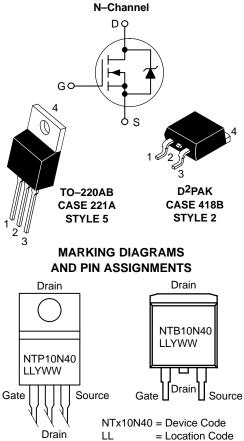
This document contains information on a new product. Specifications and information herein are subject to change without notice.



ON Semiconductor[™]

http://onsemi.com

10 AMPERES 400 VOLTS RDS(on) = 500 mΩ



= Year

WW = Work Week

ORDERING INFORMATION

Υ

Device	Package	Shipping
NTP10N40	TO-220AB 50 Units/Ra	
NTB10N40	D ² PAK	50 Units/Rail
NTB10N40T4	D ² PAK	800/Tape & Reel

Preferred devices are recommended choices for future use and best overall value.

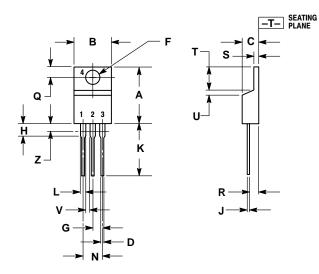
ELECTRICAL CHARACTERISTICS (T_C = 25° C unless otherwise noted)

Characteristic		Symbol	Min	Тур	Max	Unit
OFF CHARACTERISTICS						
Drain-to-Source Breakdown Voltage (V _{GS} = 0 Vdc, I _D = 0.25 mAdc) Temperature Coefficient (Positive)		V _(BR) DSS	400	_ 475	-	Vdc mV/°C
Zero Gate Voltage Collector Cur			470		μAdc	
$ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{GS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{GS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{GS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 400 \text{ Vdc}, \text{ V}_{SS} = 0 \text{ Vd} \\ (V_{DS} = 0 \text{ Vd} \\ (V_{$	c)	IDSS	-		10 100	μλάς
Gate–Body Leakage Current (V	$GS = \pm 20$ Vdc, $V_{DS} = 0$)	IGSS(f) IGSS(r)		_ _	100 100	nAdc
ON CHARACTERISTICS (Note 2	.)					
Gate Threshold Voltage $I_D = 0.25 \text{ mA}, V_{DS} = V_{GS}$ Temperature Coefficient (Neg	ative)	VGS(th)	2.0 _	2.5 6.5	4.0 _	Vdc mV/°C
Static Drain-to-Source On-Res	sistance (V _{GS} = 10 Vdc, I_D = 5.0 Adc)	R _{DS(on)}	-	350	500	mOhm
	TJ = 125°C)	VDS(on)	_		6.0 5.3	Vdc
Forward Transconductance (VD	_S = 15 Vdc, I _D = 5.0 Adc)	9FS	2.0	7.0	-	Mhos
DYNAMIC CHARACTERISTICS						
Input Capacitance		C _{iss}	_	1440	2020	pF
Output Capacitance	(V _{DS} = 25 Vdc, V _{GS} = 0 Vdc, f = 1.0 MHz)	C _{OSS}	_	360	500	-
Transfer Capacitance	T = T.0 WHZ)	C _{rss}	-	15	30	
SWITCHING CHARACTERISTIC	S (Note 3.)	I			1	1
Turn–On Delay Time		^t d(on)	_	10	20	ns
Rise Time	$(V_{DD} = 200 \text{ Vdc}, I_D = 10 \text{ Adc},$	tr	-	20	40	1
Turn–Off Delay Time	V _{GS} = 10 Vdc, R _G = 9.1 Ω)	^t d(off)	-	33	70	
Fall Time		tf	-	24	50	
Gate Charge	(V _{DS} = 320 Vdc, I _D = 10 Adc,	QT	_	24	30	nC
		Q ₁	_	6.0	_	1
	$V_{GS} = 10$ Vdc)	Q ₂	-	7.0	-	
		Q ₃	_	12	_	-
SOURCE-DRAIN DIODE CHAR	ACTERISTICS	I			I	1
Forward On–Voltage (Note 2.)	(I _S = 10 Adc, V _{GS} = 0 Vdc) (I _S = 10 Adc, V _{GS} = 0 Vdc, T _J = 125°C)	V _{SD}		0.9 0.8	1.1 -	Vdc
Reverse Recovery Time		t _{rr}	_	305	_	ns
		ta	_	155	_	1
	(I _S = 10 Adc, V _{GS} = 0 Vdc, dI _S /dt = 100 A/μs)	tb	_	150	-	
Reverse Recovery Stored Charge		Q _{RR}	_	2.5	_	μC
NTERNAL PACKAGE INDUCTA	NCE					
Internal Drain Inductance (Measured from contact screw on tab to center of die) (Measured from the drain lead 0.25" from package to center of die)		LD		3.5 4.5		nH
Internal Source Inductance (Measured from the source lea	LS		7.5		1	

Switching characteristics are independent of operating junction temperature.

PACKAGE DIMENSIONS

TO-220 THREE-LEAD TO-220AB CASE 221A-09 **ISSUE AA**



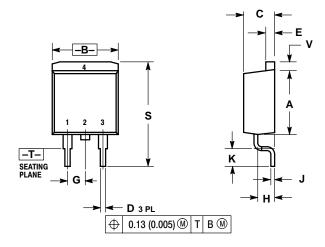
NOTES: 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982. 2. CONTROLLING DIMENSION: INCH. 3. DIMENSION Z DEFINES A ZONE WHERE ALL BODY AND LEAD IRREGULARITIES ARE ALLOWED.

	INC	HES	MILLIMETER		
DIM	MIN	MAX	MIN MA		
Α	0.570	0.620	14.48	15.75	
В	0.380	0.405	9.66	10.28	
С	0.160	0.190	4.07	4.82	
D	0.025	0.035	0.64	0.88	
F	0.142	0.147	3.61	3.73	
G	0.095	0.105	2.42	2.66	
Η	0.110	0.155	2.80	3.93	
J	0.018	0.025	0.46	0.64	
Κ	0.500	0.562	12.70	14.27	
L	0.045	0.060	1.15	1.52	
Ν	0.190	0.210	4.83	5.33	
Q	0.100	0.120	2.54	3.04	
R	0.080	0.110	2.04	2.79	
S	0.045	0.055	1.15	1.39	
Т	0.235	0.255	5.97	6.47	
U	0.000	0.050	0.00	1.27	
٧	0.045		1.15		
Ζ		0.080		2.04	

PIN 1. GATE DRAIN 2.

3. SOURCE DRAIN 4.

D²PAK CASE 418B-03 ISSUE D



NOTES: I. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
CONTROLLING DIMENSION: INCH.

	INCHES		MILLIMETERS		
DIM	MIN	MAX	MIN	MAX	
Α	0.340	0.380	8.64	9.65	
В	0.380	0.405	9.65	10.29	
С	0.160	0.190	4.06	4.83	
D	0.020	0.035	0.51	0.89	
Е	0.045	0.055	1.14	1.40	
G	0.100	0.100 BSC		2.54 BSC	
Н	0.080	0.110	2.03	2.79	
J	0.018	0.025	0.46	0.64	
Κ	0.090	0.110	2.29	2.79	
S	0.575	0.625	14.60	15.88	
٧	0.045	0.055	1.14	1.40	

STYLE 2: PIN 1. GATE 2. DRAIN 3. SOURCE 4. DRAIN

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